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BrewerBOND[®] 510

Temporary wafer bonding release material for mechanical debonding applications

KEY MARKET SECTORS

- 3-D wafer-level packaging
- MEMS
- Compound semiconductor

BENEFITS

- Compatible with 250°C - 300°C bonding materials
- Simple application on carrier substrate
- Lower cost of ownership with carrier substrate reuse
- Carrier substrate rework by RCA clean or ash
- Low-force separation

MATERIAL PROPERTIES

T_d (TGA*) = 280°C

* IPC-TM-650 2.4.24.6 (2% Loss)

n at 633 nm 1.230

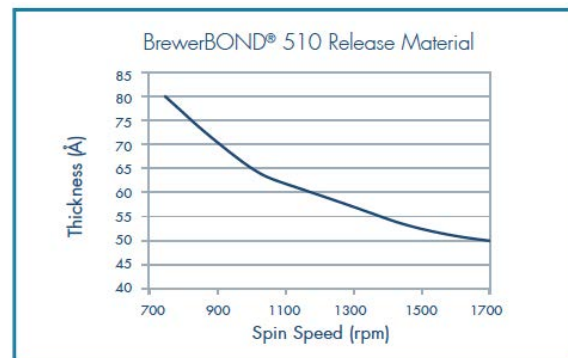
k at 633 nm 0.003

Contact Angle (with water at room temperature)

104° ± 2°

PROCESSING

Spin Speed Curve



Metrology tool: Ellipsometer (refractive index [nf] set at 1.2)

Coating Guidelines (8" substrate)

Static dispense in center of substrate

Spin Speed: See spin speed curve provided for thickness target

Acceleration: 10,000 rpm/s

Spin Time: 30 s

Hot Plate Baking Process

Proximity Bake: 205°C for 60 s

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